

Data Sheet November 19, 2004 FN2856.6

# 3.2μs Sample and Hold Amplifiers

The HA-2420 and HA-2425 is a monolithic circuit consisting of a high performance operational amplifier with its output in series with an ultra-low leakage analog switch and JFET input unity gain amplifier.

With an external hold capacitor connected to the switch output, a versatile, high performance sample-and-hold or track-and-hold circuit is formed. When the switch is closed, the device behaves as an operational amplifier, and any of the standard op amp feedback networks may be connected around the device to control gain, frequency response, etc. When the switch is opened the output will remain at its last level.

Performance as a sample-and-hold compares very favorably with other monolithic, hybrid, modular, and discrete circuits. Accuracy to better than 0.01% is achievable over the temperature range. Fast acquisition is coupled with superior droop characteristics, even at high temperatures. High slew rate, wide bandwidth, and low acquisition time produce excellent dynamic characteristics. The ability to operate at gains greater than 1 frequently eliminates the need for external scaling amplifiers.

The device may also be used as a west-tile operation amplifier with a gated output for applications such as analog switches, peak holding circuits, etc. For more information, please see Application Note AN517..

# **Ordering Information**

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. DWG.#
HA1-2420-2	-55 to 125	14 Ld CERDIP	F14.3
HA3-2425-5	0 to 75	14 Ld PDIP	E14.3

#### **Features**

•	Maximum Acquisition Time	
	- 10V Step to 0.1%	4μs (Max)
	- 10V Step to 0.01%	6μs (Max)
•	Low Droop Rate ( $C_H = 1000 pF$ ) $5\mu$	V/ms (Typ)
•	Gain Bandwidth Product 2.5	MHz (Typ)

• Low Effective Aperture Delay Time . . . . . . . 30ns (Typ)

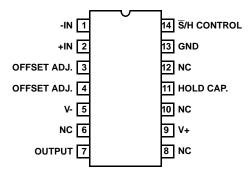
- TTL Compatible Control Input
- ±12V to ±15V Operation

### **Applications**

- 12-Bit Data Acquisition
- · Digital to Analog Deglitcher
- · Auto Zero Systems
- Peak Detector
- · Gated Operational Amplifier

### Pinout





### **Absolute Maximum Ratings**

#### 

#### **Operating Conditions**

Temperature Range	
HA-2420-2	55°C to 125°C
HA-2425-5	0°C to 75°C
Supply Voltage Range (Typical)	±12V to ±15V

#### **Thermal Information**

Thermal Resistance (Typical, Note 1)	θ <sub>JA</sub> (°C/W)	θ <sub>JC</sub> (oC/W)
CERDIP Package	75	20
PDIP Package	95	N/A
Maximum Junction Temperature (Ceramic F		175°C
Maximum Junction Temperature (Plastic P	ackage)	150°C
Maximum Storage Temperature Range	65	<sup>o</sup> C to 150 <sup>o</sup> C
Maximum Lead Temperature (Soldering 10	0s)	300°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

1. θ<sub>JA</sub> is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.

**Electrical Specifications** Test Conditions (Unless Otherwise Specified)  $V_{SUPPLY} = \pm 15.0V$ ;  $C_H = 1000pF$ ; Digital Input:  $V_{IL} = +0.8V$  (Sample),  $V_{IH} = +2.0V$  (Hold), Unity Gain Configuration (Output tied to Negative Input)

	TEST	TEMP.	HA-2420-2			HA-2425-5			
PARAMETER	CONDITIONS	(°C)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
INPUT CHARACTERISTICS	1	II I		1	'	Į.	и	U.	U.
Input Voltage Range		Full	±10	-	-	±10	-	-	V
Offset Voltage		25	-	2	4	-	3	6	mV
		Full	-	3	6	-	4	8	mV
Bias Current		25	-	40	200	-	40	200	nA
	DDTIC	Full	-	/   .	400	·		400	nA
Offset Current WWW	BUILL	25		1)	£0 <b>(</b>	ers	0	50	nA
		Full	-	-	100	-	-	100	nA
Input Resistance		25	5	10	-	5	10	-	MΩ
Common Mode Range		Full	±10	-	-	±10	-	-	V
TRANSFER CHARACTERISTICS		1			1	I			Ш
Large Signal Voltage Gain	$R_L = 2k\Omega$ , $V_O = 20V_{P-P}$	Full	25	50	-	25	50	-	kV/V
Common Mode Rejection	$V_{CM} = \pm 10V$	Full	80	90	-	74	90	-	dB
Hold Mode Feedthrough Attenuation (Note 2)	$f_{IN} \leq 100 kHz$	Full	-	-76	-	-	-76	-	dB
Gain Bandwidth Product (Note 2)		25	-	2.5	-	-	2.5	-	MHz
OUTPUT CHARACTERISTICS									
Output Voltage Swing	$R_L = 2k\Omega$	Full	±10	-	-	±10	-	-	V
Output Current		25	±15	-	-	±15	-	-	mA
Full Power Bandwidth (Note 2)	V <sub>O</sub> = 20V <sub>P-P</sub>	25	-	100	-	-	100	-	kHz
Output Resistance	DC	25	-	0.15	-	-	0.15	-	Ω
TRANSIENT RESPONSE									
Rise Time (Note 2)	$V_O = 200 \text{mV}_{P-P}$	25	-	75	100	-	75	100	ns
Overshoot (Note 2)	$V_{O} = 200 \text{mV}_{P-P}$	25	-	25	40	-	25	40	%
Slew Rate (Note 2)	$V_{O} = 10V_{P-P}$	25	3.5	5	-	3.5	5	-	V/μs

### **Electrical Specifications**

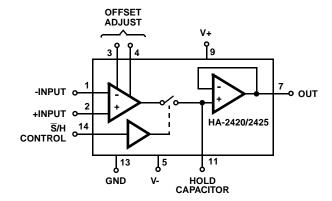
Test Conditions (Unless Otherwise Specified)  $V_{SUPPLY} = \pm 15.0V$ ;  $C_H = 1000pF$ ; Digital Input:  $V_{IL} = +0.8V$  (Sample),  $V_{IH} = +2.0V$  (Hold), Unity Gain Configuration (Output tied to Negative Input) (Continued)

	TEST	TEMP.	HA-2420-2		HA-2425-5				
PARAMETER	CONDITIONS	(°C)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
DIGITAL INPUT CHARACTERIS	TICS	•	<u>'</u>	'	'	<u>'</u>	'	•	
Digital Input Current	$V_{IN} = 0V$	Full	-	-	-0.8	-	-	-0.8	mA
	V <sub>IN</sub> = 5V	Full	-	-	20	-	-	20	μА
Digital Input Voltage	Low	Full	-	-	0.8	-	-	0.8	V
	High	Full	2.0	-	-	2.0	-	-	V
SAMPLE AND HOLD CHARACT	ERISTICS	+	!	+	'	!	+		+
Acquisition Time (Note 2)	To 0.1% 10V Step	25	-	2.3	4	-	2.3	4	μS
Acquisition Time (Note 2)	To 0.01% 10V Step	25	-	3.2	6	-	3.2	6	μS
Hold Step Error	V <sub>IN</sub> = 0V	25	-	10	20	-	10	20	mV
Hold Mode Settling Time	To ±1mV	25	-	860	-	-	860	-	ns
Aperture Time (Note 3)		25	-	30	-	-	30	-	ns
Effective Aperture Delay Time		25	-	30	-	-	30	-	ns
Aperture Uncertainty		25	-	5	-	-	5	-	ns
Drift Current (Note 2)	V <sub>IN</sub> = 0V	25	-	5	-	-	5	-	рА
HA1-2420		Full	-	1.8	10	-	-	-	nA
HA1-2425		Full	-	-	-	-	0.1	1.0	nA
HA3-2425, HA4P2425,		Full	-	, -	-	-	7.5	10.0	nA
POWER SUPPLY : ARICYLERI	BOTIC		<del>m</del>	<b>/                                    </b>	<u>ጎ †                                   </u>	re	\ i		
							<b>)</b>	<u> </u>	1
Supply Current (+)		25	-	3.5	5.5	-	3.5	5.5	mA
Supply Current (-)		25	-	2.5	3.5	-	2.5	3.5	mA
Power Supply Rejection		Full	80	90	-	74	90	-	dB

#### NOTES:

- 2. A<sub>V</sub> =  $\pm 1$ , R<sub>L</sub> =  $2k\Omega$ , C<sub>L</sub> = 50pF.
- 3. Derived from computer simulation only; not tested.

# **Functional Diagram**



### Test Circuits and Waveforms

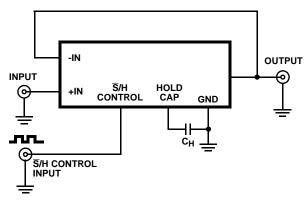
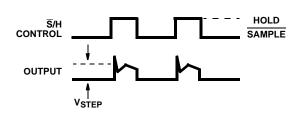
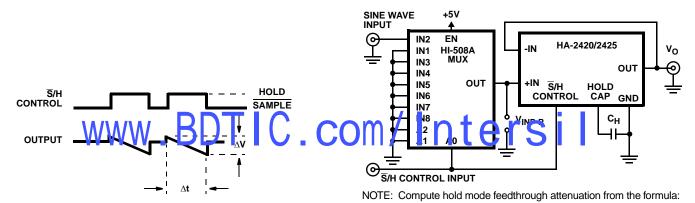


FIGURE 1. HOLD STEP ERROR AND DRIFT CURRENT



NOTE: Set rise/fall times of \$\overline{S}\$/H Control to approximately 20ns.

#### FIGURE 2. HOLD STEP ERROR TEST



NOTE: Measure the slope of the output during hold,  $\Delta V/\Delta t$ , and compute drift current from:  $I_D = C_H \ \Delta V/\Delta t$ .

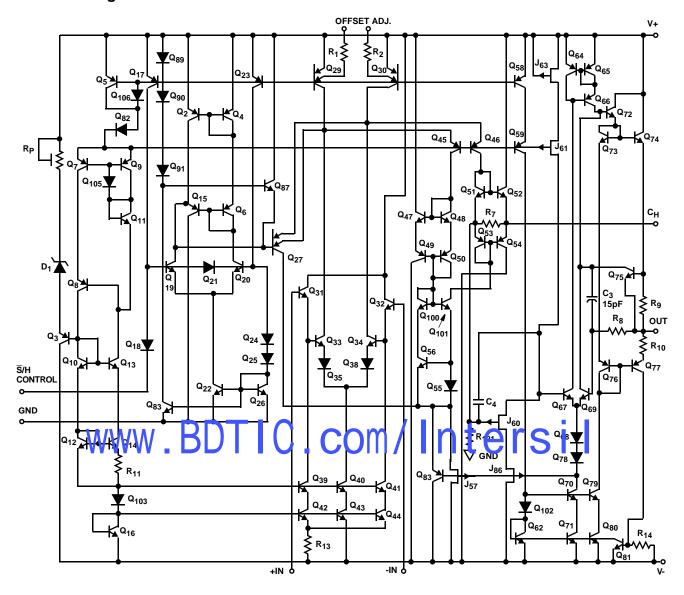
FIGURE 3. DRIFT CURRENT TEST

Feedthrough Attenuation =  $20 log \frac{V_{OUT}HOLD}{V_{IN}HOLD}$ 

Where  $V_{OUT}HOLD$  = Peak-to-Peak value of output sinewave during the hold mode.

FIGURE 4. HOLD MODE FEEDTHROUGH ATTENUATION

# Schematic Diagram



# Application Information

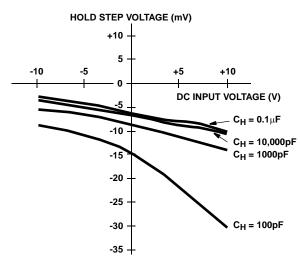


FIGURE 5. HOLD STEP vs INPUT VOLTAGE

#### Offset Adjustment

The offset voltage of the HA-2420 and HA-2425 may be adjusted using a  $100 k\Omega$  trim pot, as shown in Figure 8. The recommended adjustment procedure is:

Apply 0V to the sample-and-hold input, and a square wave to the  $\overline{S}/H$  control.

Adjust the trim pot for 0V output in the held mede

# Gain Adjustmen WW \_ BD | C

The linear variation in pedestal voltage with sample-and-hold input voltage causes a -0.06% gain error ( $C_H = 1000 pF$ ). In some applications (D/A deglitcher, A/D converter) the gain error can be adjusted elsewhere in the system, while in other applications it must be adjusted at the sample-and-hold. The two circuits shown below demonstrate how to adjust gain error at the sample-and-hold.

The recommended procedure for adjusting gain error is:

- 1. Perform offset adjustment.
- Apply the nominal input voltage that should produce a +10V output.
- 3. Adjust the trim pot for +10V output in the hold mode.
- Apply the nominal input voltage that should produce a -10V output.
- 5. Measure the output hold voltage (V<sub>-10NOMINAL</sub>). Adjust the trim pot for an output hold voltage of

$$\frac{(V_{-10NOMINAL}) + (-10V)}{2}$$

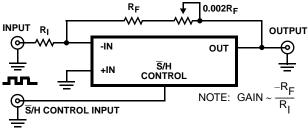


FIGURE 6. INVERTING CONFIGURATION

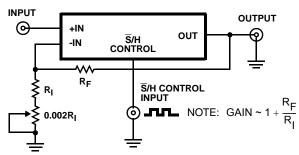


FIGURE 7. NON-INVERTING CONFIGURATION

Figure 8 shows a typical unity gain circuit, with Offset Zeroing. All of the other normal op amp feedback configurations may be used with the HA-2420, HA-2425. The input amplifier may be used as a gated amplifier by utilizing Pin 11 as the output. This amplifier has excellent drive apabilities along with exceptionary lows vitch leakage.

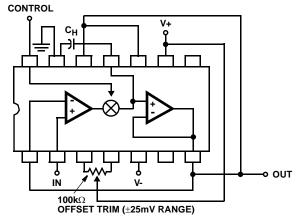


FIGURE 8. BASIC SAMPLE-AND-HOLD (TOP VIEW)

The method used to reduce leakage paths on the PC board and the device package is shown in Figure 9. This guard ring is recommended to minimize the drift during hold mode.

The hold capacitor should have extremely high insulation resistance and low dielectric absorption. Polystyrene (below 85°C), Teflon, or Parlene types are recommended.

For more applications, consult Intersil Application Note AN517, or the factory applications group.

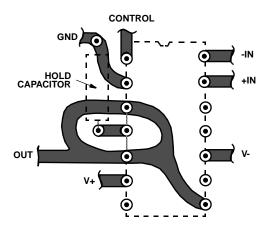


FIGURE 9. GUARD RING LAYOUT (BOTTOM VIEW)

### Glossary of Terms

### **Acquisition Time**

The time required following a "sample" command, for the output to reach its final value within  $\pm 0.1\%$  or  $\pm 0.01\%$ . This is the minimum sample time required to obtain a given accuracy, and includes switch delay time, slewing time and settling time.

#### **Aperture Time**

The time required for the sample-and-hold switch to open, independent of delays through the switch driver and input amplifier circuitry. The switch opening time is that interval between the conditions of 10% opening the part of 50% open.

#### Effective Aperture Delay Time (EADT)

The difference between the digital delay time from the Hold command to the opening of the S/H switch, and the propagation time from the analog input to the switch.

EADT may be positive, negative or zero. If zero, the S/H amplifier will output a voltage equal to  $V_{IN}$  at the instant the Hold command was received. For negative EADT, the output in Hold (exclusive of pedestal and droop errors) will correspond to a value of  $V_{IN}$  that occurred before the Hold command.

### **Aperture Uncertainty**

The range of variation in Effective Aperture Delay Time. Aperture Uncertainty (also called Aperture Delay Uncertainty, Aperture Time Jitter, etc.) sets a limit on the accuracy with which a waveform can be reconstructed from sample data.

#### **Drift Current**

The net leakage current from the hold capacitor during the hold mode. Drift current can be calculated from the droop rate using the formula:

$$I_D (pA) = C_H (pF) \times \frac{\Delta V}{\Delta t} (V/s)$$

between the contribute of 10% opening to the switch opening to the

# **Typical Performance Curves**

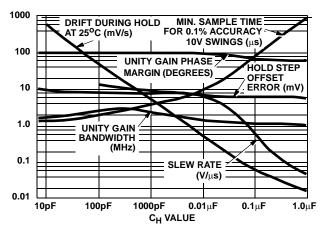


FIGURE 10. TYPICAL SAMPLE AND HOLD PERFORMANCE
AS A FUNCTION OF HOLDING CAPACITOR

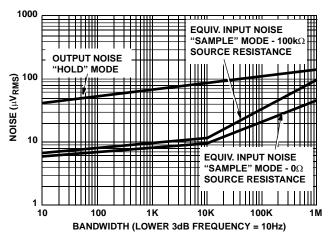


FIGURE 11. BROADBAND NOISE CHARACTERISTICS

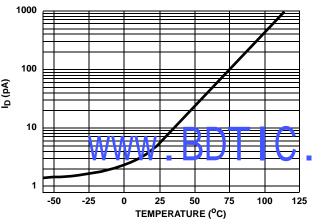


FIGURE 12. DRIFT CURRENT vs TEMPERATURE

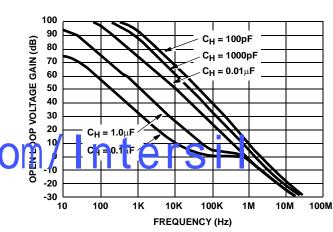


FIGURE 13. OPEN LOOP FREQUENCY RESPONSE

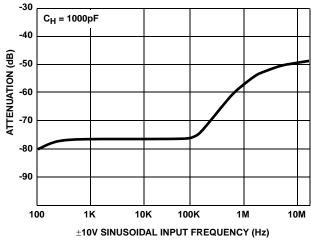


FIGURE 14. HOLD MODE FEED THROUGH ATTENUATION

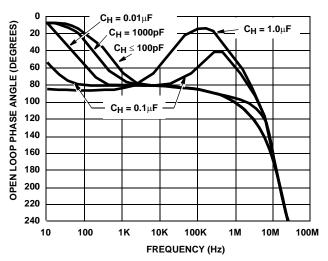


FIGURE 15. OPEN LOOP PHASE RESPONSE



# Typical Performance Curves (Continued)

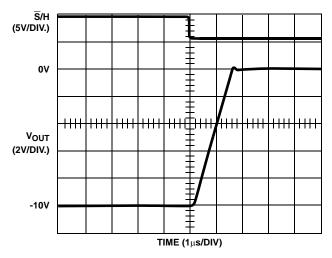


FIGURE 16. ACQUISITION TIME (C<sub>H</sub> = 1000pF)

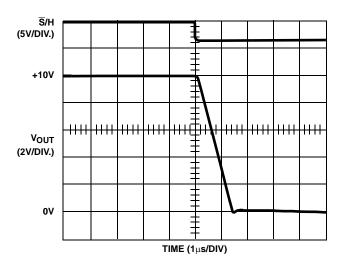


FIGURE 17. ACQUISITION TIME (C<sub>H</sub> = 1000pF)

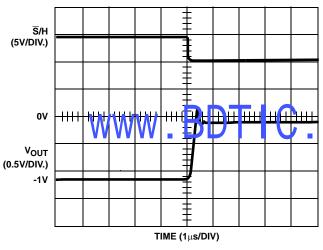


FIGURE 18. ACQUISITION TIME (CH = 1000pF)

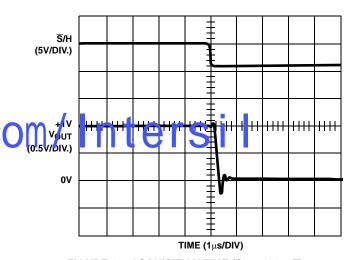


FIGURE 19. ACQUISITION TIME ( $C_H = 1000pF$ )

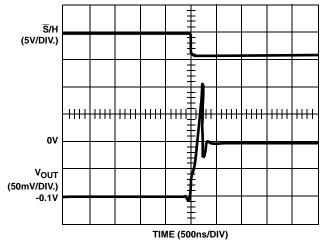


FIGURE 20. ACQUISITION TIME (C<sub>H</sub> = 1000pF)

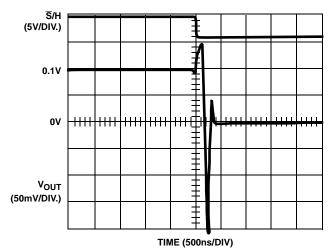


FIGURE 21. ACQUISITION TIME (C<sub>H</sub> = 1000pF)

### Die Characteristics

#### **DIE DIMENSIONS:**

102 mils x 61 mils x 19 mils 2590μm x 1550μm x 483μm

#### **METALLIZATION:**

Type: Al, 1% Cu Thickness: 16kÅ ±2kÅ

### **SUBSTRATE POTENTIAL:**

٧.

#### **BACKSIDE FINISH:**

Gold, Nickel, Silicon, etc.

# Metallization Mask Layout

#### PASSIVATION:

Type: Nitride (Si<sub>3</sub>N<sub>4</sub>) over Silox (SiO<sub>2</sub>, 5% Phos.)

Silox Thickness: 12kÅ ±2kÅ Nitride Thickness: 3.5kÅ ±1.5kÅ

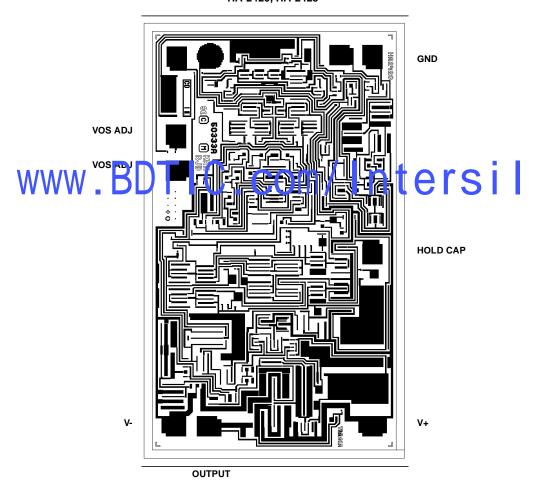
#### TRANSISTOR COUNT:

78

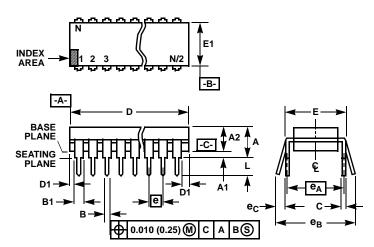
#### PROCESS:

Bipolar Dielectric Isolation

HA-2420, HA-2425



### Dual-In-Line Plastic Packages (PDIP)



#### NOTES:

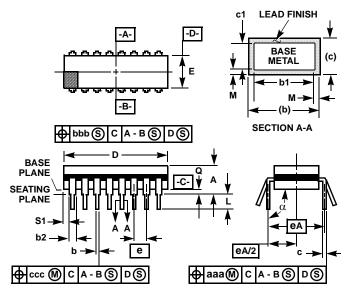
- 1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- 3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
- Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
- D, D1, and E1 dimensions do not include mold flash or protrusions.
   Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
- 6. E and e<sub>A</sub> are measured with the leads constrained to be perpendicular to datum -C-.
- 7. e<sub>B</sub> and e<sub>C</sub> are measured at the least on with the least constrained. e<sub>C</sub> must be zero of greaters with the least constrained.
- 8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
- 9. N is the maximum number of terminal positions.
- 10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 0.045 inch (0.76 1.14mm).

E14.3 (JEDEC MS-001-AA ISSUE D)
14 LEAD DUAL-IN-LINE PLASTIC PACKAGE

	INCHES MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
В	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8
С	0.008	0.014	0.204	0.355	-
D	0.735	0.775	18.66	19.68	5
D1	0.005	-	0.13	-	5
Е	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
е	0.100	BSC	2.54 BSC		-
e <sub>A</sub>	0.300	BSC	7.62 BSC		6
e <sub>B</sub>	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	1	14		14	

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# Ceramic Dual-In-Line Frit Seal Packages (CERDIP)



#### NOTES:

- Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
- The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
- 3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plantage of finish thickness.
- 4. Corner leads (1 N, N/2, and N/2+1, play be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
- 5. This dimension allows for off-center lid, meniscus, and glass
- 6. Dimension Q shall be measured from the seating plane to the base plane.
- 7. Measure dimension S1 at all four corners.
- 8. N is the maximum number of terminal positions.
- 9. Dimensioning and tolerancing per ANSI Y14.5M 1982.
- 10. Controlling dimension: INCH.

F14.3 MIL-STD-1835 GDIP1-T14 (D-1, CONFIGURATION A) 14 LEAD CERAMIC DUAL-IN-LINE FRIT SEAL PACKAGE

	INC	HES	MILLIM		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
С	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.785	-	19.94	5
Е	0.220	0.310	5.59	7.87	5
е	0.100	BSC	2.54 BSC		-
eA	0.300	BSC	7.62	BSC	-
eA/2	0.150	BSC	3.81	BSC	-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
α	90°	105 <sup>0</sup>	90°	105 <sup>0</sup>	-
aaa	-	0.015	-	0.38	-
bbb	_	0.030		0.76	-
<b>M</b> ccc	ln t	2.010	C	0.25	-
M	1 1-1 (	0.0015	3-1	0.038	2, 3
N	1	4	1	8	

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